

**RELIABILITY MONITOR REPORT
FOR**

TSOP Package

Dallas Semiconductor

**4401 South Beltwood Parkway
Dallas, TX 75244-3292**

**This Report was prepared by
Dallas Semiconductor Reliability Engineering**

Summary:

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The assemblies covered by this package monitor are:

ASSY SITE	PINS	PACKAGE		
ATK (Amkor, K)	28	TSOP	ATK (Amkor, K)	32 TSOP
ATP (Amkor, PI)	28	TSOP	ATP (Amkor, PI)	32 TSOP
NSEB	28	TSOP	NSEB	32 TSOP

The calculated failure rate for this assembly is:

The parameters used to calculate this failure rate are as follows:

Cf: 60% **Ea: 0.7** **B: 0** **Tu: 25 °C** **Vu: 5.5 Volts**

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 10/1/03 and 9/30/04 .

Assembly Information:

Package Type: TSOP 8 mm
Flammability: UL 94-V0
Moisture Sensitivity
(JEDEC J-STD20A) Level 3
Date Code Range: 0432 to 0432

PACKAGE TESTS

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
SOLDERABILITY	0432	DS1501	JESD22-B102		8	0	
				Total:		0	